

**REMARKS**

This Amendment is in response to the Office Action mailed on November 25, 2008. Claim 1 is amended and is supported, for example, in the specification on page 11, lines 7-10, 29-30 and in Figure 1. Claims 6, 7, 10 and 11 are cancelled without prejudice or disclaimer. No new matter is added. Claims 1-5, 8 and 9 are pending.

**§102 Rejections:**

Claims 1, 8 and 9 are rejected as being anticipated by Takahashi (US Patent No. 5,903,239). This rejection is traversed.

Claim 1 is directed to a module that requires, among other features, a substrate and a plurality of semiconductor packages, each comprising a semiconductor chip, mounted on the substrate. Each of the plurality of semiconductor packages comprises a first radio communication element that is constituted independently of the semiconductor chip so as to transmit and receive a signal between the semiconductor chips in the plurality of semiconductor packages by radio communication. Also, the first radio communication element comprises an antenna and an RF circuit.

Takahashi does not disclose or suggest these features. Takahashi is directed to a millimeter wave detector having an antenna. The millimeter wave detector includes a first semiconductor substrate 1 made of silicon, a ground conductor film 2 formed on the substrate 1, a dielectric film 3 formed on the film 2, and a planar antenna 4 and a microstrip line 7 formed on the dielectric film 3. The millimeter wave detector also includes a circuit chip 51 flip-chip mounted on the first semiconductor substrate 1, the circuit chip 51 including a detector circuit 62 and a second semiconductor substrate 5 made of gallium arsenide (GaAs) (See Figure 1 of Takahashi).

The rejection interprets the circuit chip 52, the substrate 5 and the detecting circuit 62 as the plurality of semiconductor packages, the semiconductor chip and the first radio communication element, respectively of claim 1. However, the substrate 5 cannot be semiconductor chip of claim 1, as a semiconductor chip, by definition, is not merely a substrate. Also, the detecting circuit 62 of Takahashi cannot be interpreted as both the semiconductor chip and the first communication element of claim 1 as claim 1 requires the first communication element be constituted independently of the semiconductor chip.

Thus, Takahashi cannot disclose or suggest the plurality of semiconductor packages of claim 1, as Takahashi cannot disclose a semiconductor package having a semiconductor chip and a first communication element that is constituted independently of the semiconductor chip.

Moreover, Takahashi also does not disclose or suggest that the detector circuit 62 includes an antenna and an RF circuit, as required by the first communication element of claim 1. In contrast, Takahashi discloses that the detector circuit 62 is electrically connected to the planar antenna 4 (see column 3, lines 31-39 of Takahashi). For at least these reasons claim 1 is not suggested by Takahashi and should be allowed. Claims 8 and 9 depend from claim 1 and should be allowed for at least the same reasons.

§103 Rejections:

Claims 2-5 are rejected as being unpatentable over Takahashi in view of Park (US Patent No. 7,365,683). This rejection is traversed. Claims 2-5 depend from claim 1 and should be allowed for at least the same reasons discussed above. Applicants do not concede the correctness of this rejection.

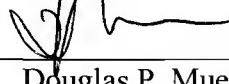
Conclusion:

Applicants respectfully assert that claims 1-5, 8 and 9 are in condition for allowance. If a telephone conference would be helpful in resolving any issues concerning this communication, please contact Applicants' primary attorney-of record, Douglas P. Mueller (Reg. No. 30,300), at (612) 455-3804.

Respectfully submitted,



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